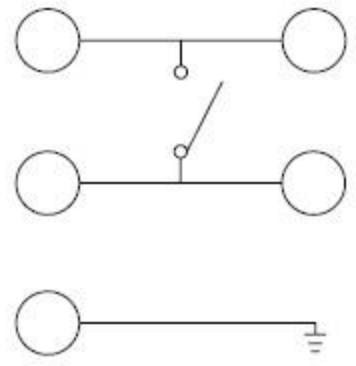
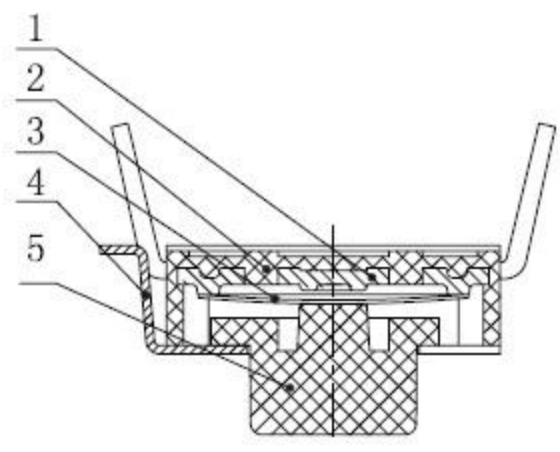


1
2



-20°C to +70°C
50mA, 12V DC
100MΩ min, 100V DC
250V AC for 1 min
100MΩ max
0.25±0.1mm
2.5/2.7/3.0/3.1/3.4/3.7/3.8/4.3/5/5.5/6/7mm
100gf/160gf/260gf

Conditions for Auto-dip	
Items	Condition
Flux built-up	Mounting surface should not be coated with flux
Preheating temperature	印刷电路板焊接面的周围温度 100°C max. Ambient temperature of the soldered surface of PC board. 100°C max.
Preheating time	60s max.
Soldering temperature	260°C max.
Continuous dipping time Number of soldering	5s max. 焊接次数 2次以下 / 2times max.
Hand soldering	
请按以下条件进行焊接： (1) 焊锡温度：≤350°C (2) 连续焊接时间：≤3 s Please practice according to below conditions: (1) Soldering temperature: 350°C Max. (2) Continuous soldering time: 3 s Max.	